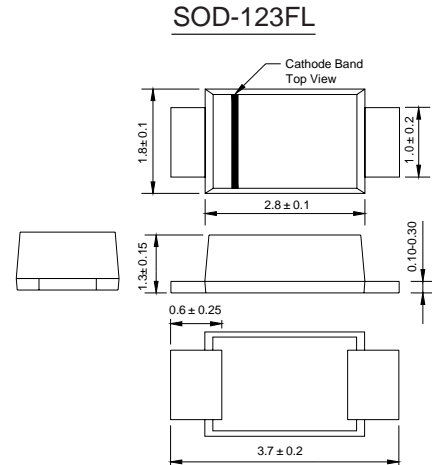


## FEATURES

- ◆ Glass passivated device
- ◆ Ideal for surface mounted applications
- ◆ Low reverse leakage
- ◆ Metallurgically bonded construction
- ◆ High temperature soldering guaranteed:  
250°C/10 seconds, 0.375" (9.5mm) lead length,  
5 lbs. (2.3kg) tension

## MECHANICAL DATA

**Case:** JEDEC SOD-123FL molded plastic body over passivated chip  
**Terminals:** Plated axial leads, solderable per MIL-STD-750,  
Method 2026  
**Polarity:** Color band denotes cathode end  
**Mounting Position:** Any  
**Weight:** 0.0007 ounce, 0.02 grams



Dimensions in millimeters

## MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Ratings at 25°C ambient temperature unless otherwise specified.  
Single phase half-wave 60Hz, resistive or inductive load, for capacitive load current derate by 20%.

	SYMBOLS	ES1AL EA	ES1BL EB	ES1CL EC	ES1DL ED	ES1EL EE	ES1GL EG	ES1JL EJ	UNITS
Maximum repetitive peak reverse voltage	$V_{RRM}$	50	100	150	200	300	400	600	VOLTS
Maximum RMS voltage	$V_{RMS}$	35	70	105	140	210	280	420	VOLTS
Maximum DC blocking voltage	$V_{DC}$	50	100	150	200	300	400	600	VOLTS
Maximum average forward rectified current	$I_{(AV)}$	1.0							Amp
Peak forward surge current 8.3ms single half sine-wave superimposed on rated load (JEDEC Method)	$I_{FSM}$	25.0							Amps
Maximum instantaneous forward voltage at 1.0A	$V_F$	0.95			1.25		1.7		Volts
Maximum DC reverse current $T_A=25^\circ\text{C}$ at rated DC blocking voltage $T_A=100^\circ\text{C}$	$I_R$	5.0 100.0							$\mu\text{A}$
Maximum reverse recovery time (NOTE 1)	$t_{rr}$	35							ns
Typical junction capacitance (NOTE 2)	$C_J$	10							pF
Typical thermal resistance (NOTE 3)	$R_{\theta JA}$	85							K/W
Operating junction and storage temperature range	$T_J, T_{STG}$	-55 to +150							$^\circ\text{C}$

**Note:** 1. Measured with  $I_F=0.5\text{A}$ ,  $I_R=1\text{A}$ ,  $I_{rr}=0.25\text{A}$ .  
2. Measured at 1MHz and applied reverse voltage of 4.0V D.C.  
3. PCB mounted on 0.2\*0.2" (5.0\*5.0mm) copper pad area.



FIG. 1- FORWARD CURRENT DERATING CURVE

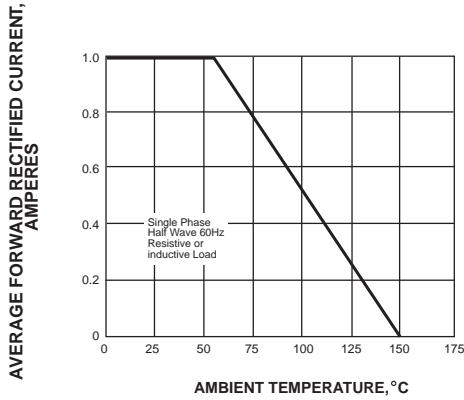


FIG. 2-MAXIMUM NON-REPETITIVE PEAK FORWARD SURGE CURRENT

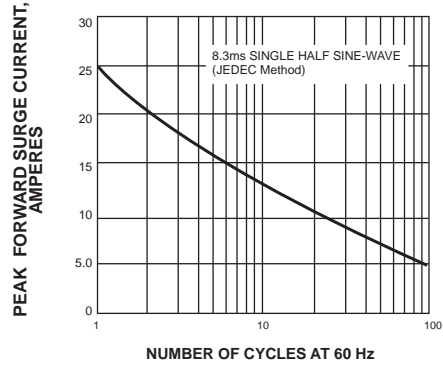


FIG. 3-TYPICAL INSTANTANEOUS FORWARD CHARACTERISTICS

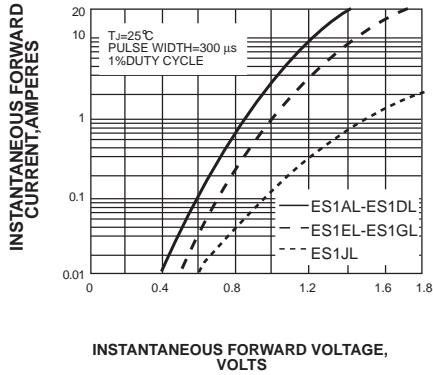


FIG. 4-TYPICAL REVERSE CHARACTERISTICS

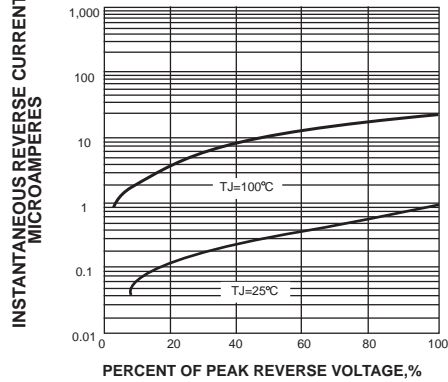


FIG. 5-TYPICAL JUNCTION CAPACITANCE

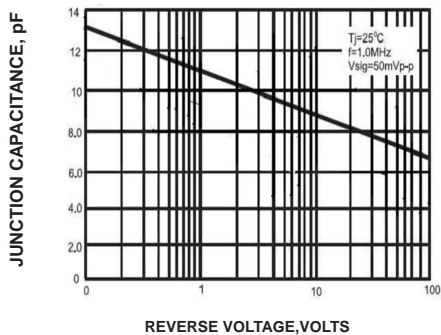


FIG. 6-TYPICAL TRANSIENT THERMAL IMPEDANCE

